P/1071-1586

PA *)VER SHEET* 102334398 To the Assistant Commissioner of Patents and Trademarks: Please record the attached original document or copy thereof. 1. Name of conveying party(ies): 2. Name and Address of receiving party(ies): Murata Manufacturing Co., Ltd. Makoto INAI Eiji TAI 26-10, Tenjin 2-chome Hidehiko SASAKI Nagaokakyo-shi Kyoto-fu, 617-8555 Japan Type of Entity: Corporation-Japan Type of Entity: Individual Additional names(s) of conveying party(ies) attached? Additional name(s) & address(es) attached? Nο 3. Nature of Conveyance: Assignment **Execution Date:** December 25, 2002 Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: December 25, 2002 B. Patent No.(s) A. Application No.(s) Additional numbers attached? No Total number of documents involved: Name and address of party to whom

correspondence concerning document should be mailed:

OSTROLENK, FABER, GERB & SOFFEN, LLP 1180 Avenue of the Americas New York, New York 10036-8403

7. Total fee (37 CFR 3.41):

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8. To the best of my knowledge and belief, the foregoing into atiph is true and correct and any attached copy is a true copy of the original document.

James A. Finder

Name of Person Signing

Signature

December 30, 2002

Date

Total number of pages including cover sheet, attachments, and document:

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00595650.1

PATENT REEL: 013635 FRAME: 0250 WHEREAS, we, Makoto INAI, Eiji TAI and Hidehiko SASAKI as assignors, have invented certain improvements in MASKING MEMBER FOR FORMING FINE ELECTRODE AND MANUFACTURING METHOD THEREFOR, METHOD FOR FORMING ELECTRODE, AND FIELD EFFECT TRANSISTOR for which an application for United States Letters Patent has been executed by me of even date herewith; and

WHEREAS, Murata Manufacturing Co., Ltd., a corporation organized under the laws of Japan and having a principal place of business at 26-10, Tenjin 2-chome, Nagaokakyo-shi, Kyoto-fu, 617-8555, Japan, as assignee, is desirous of acquiring all right, title and interest in and to said invention and any Patent that may be granted therefor.

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, we, as assignors, hereby sell, assign and set over to said assignee the entire right, title and interest for the United States and all other countries in and to said invention and the aforesaid application for Patent, all original, divisional, continuation, substitute or reissue applications and patents applied for or granted therefor in the United States and all other countries, including all rights of priority from the filing of said application, and all rights for pas infringement, and the Commissioner of Patents and Trademarks is hereby authorized and requested to issue all patents on said inventions or resulting therefrom to said assignee herein, as assignee of the entire interest therein; and the undersigned for ourselves and our legal representatives, heirs and assigns do hereby agree and covenant without further remuneration, to execute and deliver all divisional, continuation, reissue and other applications for Patent on said inventions and all assignments thereof to said assignee or its assigns, to communicate to said assignee or its representatives all facts known to the undersigned respecting said inventions, whenever requested, to testify in any interferences or other legal proceedings in which any of said applications or patents may become involved, to sign all lawful papers, make all rightful oaths, and to do generally everything necessary to assist assignee, its successors, assigns and nominees to obtain patent protection for said invention in the United States and all other countries, the expenses incident to said applications to be borne and paid by said assignee.

25/December / 2002

(Date)

25/December / 2002

(Date)

25/December / 2002

(Date)

Makoto / mai

Eiji Tai

Hidehiko Naroki

{00593906.1}

PATENT REEL: 013635 FRAME: 0251